Gap Pad® VO

Conformable, Thermally Conductive Material for Filling Air Gaps

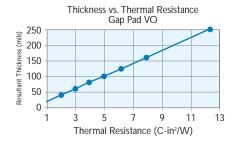
Features and Benefits

- Thermal conductivity: 0.8 W/m-K
- Enhanced puncture, shear and tear resistance
- · Conformable gap filling material
- · Electrically isolating



Gap Pad VO is a cost-effective, thermally conductive interface material. The material is a filled, thermally conductive polymer supplied on a rubber-coated fiberglass carrier allowing for easy material handling. The conformable nature of Gap Pad VO allows the pad to fill in air gaps between PC boards and heat sinks or a metal chassis.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD VO			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Gold/Pink	Gold/Pink	Visual
Reinforcement Carrier	Sil-Pad	Sil-Pad	_
Thickness (inch) / (mm)	0.020 to 0.250	0.508 to 6.350	ASTM D374
Inherent Surface Tack (1- or 2-sided)	1	1	_
Density (g/cc)	1.6	1.6	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness, Bulk Rubber (Shore 00) (1)	40	40	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	100	689	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	_
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149
Dielectric Constant (1000 Hz)	5.5	5.5	ASTM D150
Volume Resistivity (Ohm-meter)	1011	1011	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL	_		
Thermal Conductivity (W/m-K)	0.8	0.8	ASTM D5470
1) Thirty second delay value Shore 00 hardness scale	_		

Thirty second delay value Shore 00 hardness scale

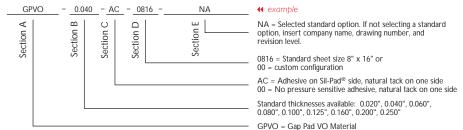
Typical Applications Include:

- Telecommunications
- · Computer and peripherals
- Power conversion
- Between heat-generating semiconductors and a heat sink
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader
- Between heat-generating magnetic components and a heat sink

Configurations Available:

• Sheet form and die-cut parts

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others



Standard Options

²⁾ Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch? For more information on Gap Pad modulus, refer to Bergquist Application Note #116.